

PNP SILICON EPITAXIAL TRANSISTOR **2SA1836**

PNP SILICON EPITAXIAL TRANSISTOR

DESCRIPTION

The 2SA1836 is PNP silicon epitaxial transistor.

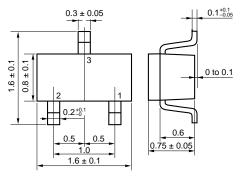
FEATURES

- High DC current gain: hFE2 = 200 TYP.
- High voltage: VCEO = -50 V

ABSOLUTE MAXIMUM RATINGS (TA = 25°C)

Collector to Base Voltage	Vсво	-60	V	
Collector to Emitter Voltage	Vceo	-50	V	
Emitter to Base Voltage	Vево	-5.0	V	
Collector Current (DC)	IC(DC)	-100	mA	
Collector Current (pulse) Note1	C(pulse)	-200	mA	
Total Power Dissipation (T _A = 25° C) ^{Note2}	P⊤	200	mW	
Total Power Dissipation (T _A = 25°C) ^{Note2} Junction Temperature	Ρτ Tj	200 150	mW °C	

PACKAGE DRAWING (Unit: mm)



1: Emitter 2: Base 3: Collector

Notes 1. PW \leq 10 ms, Duty Cycle \leq 50%

2. When mounted on ceramic substrate of $3.0 \text{ cm}^2 \times 0.64 \text{ mm}$

ELECTRICAL CHARACTERISTICS (TA = 25°C)

CHARACTERISTICS	SYMBOL	TEST CONDITIONS M		TYP.	MAX.	UNIT
Collector Cut-off Current	Ісво	$V_{CB} = -60 \text{ V}, \text{ I}_{E} = 0$			-100	nA
Emitter Cut-off Current	Іево	$V_{EB} = -5.0 \text{ V}, \text{ Ic} = 0$			-100	nA
DC Current Gain ^{Note}	hfe1	$V_{CE} = -6.0 \text{ V}, \text{ Ic} = -0.1 \text{ mA}$	50			-
	hfe2	$V_{CE} = -6.0 \text{ V}, \text{ Ic} = -1.0 \text{ mA}$	90	200	600	-
Base to Emitter Voltage ^{Note}	VBE	Vce = -6.0 V, Ic = -1.0 mA		-0.62		V
Collector Saturation Voltage	VCE(sat)	$I_{C} = -100 \text{ mA}, I_{B} = -10 \text{ mA}$		-0.18	-0.3	V
Base Saturation Voltage Note	V _{BE(sat)}	Ic = -100 mA, Iв = -10 mA		-0.86	-1.0	V
Gain Bandwidth Product	f⊤	Vce = -6.0 V, Ie = 10 mA		180		MHz
Output Capacitance	Cob	$V_{CE} = -6.0 \text{ V}, \text{ Ie} = 0, \text{ f} = 1.0 \text{ MHz}$		4.5	6.0	pF

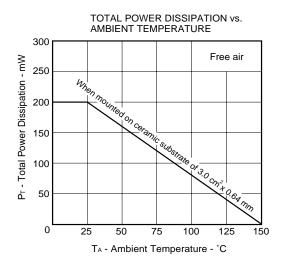
Note Pulsed: PW \leq 350 μ s, Duty Cycle \leq 2%

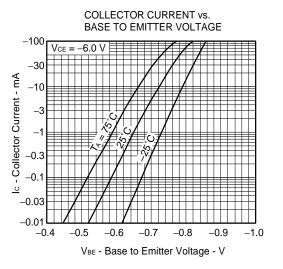
hfe CLASSFICATION

Marking	M4	M5	M6	M7
hfe2	90 to 180	135 to 270	200 to 400	300 to 600

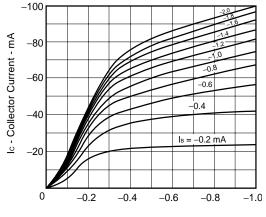
The information in this document is subject to change without notice. Before using this document, please confirm that this is the latest version. Not all devices/types available in every country. Please check with local NEC representative for availability and additional information.

TYPICAL CHARACTERISTICS (TA = 25°C)



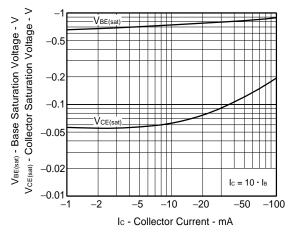


COLLECTOR CURRENT vs. COLLECTOR TO EMITTER VOLTAGE

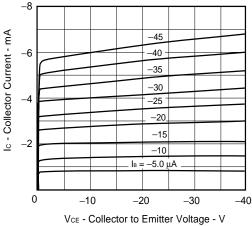


VCE - Collector to Emitter Voltage - V

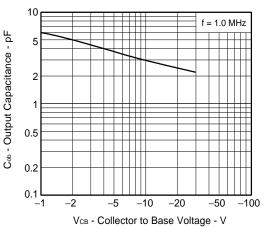
COLLECTOR AND BASE SATURATION VOLTAGE vs. COLLECTOR CURRENT



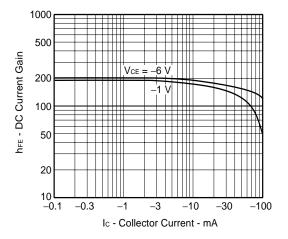




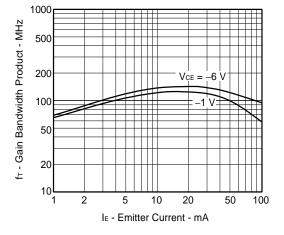
OUTPUT CAPACITANCE vs. REVERSE VOLTAGE



DC CURRENT GAIN vs. COLLECTOR CURRENT







1000 $V_{CE} = -6.0 V$ <u>T</u>_A = 75°C 500 25°C hre - DC Current Gain -25°C Ш 200 100 50 20 10 L -0.1 -0.3 -1 -3 -10 -30 -100 Ic - Collector Current - mA

DC CURRENT GAIN vs. COLLECTOR CURRENT

The information in this document is current as of July, 2001. The information is subject to change
without notice. For actual design-in, refer to the latest publications of NEC's data sheets or data
books, etc., for the most up-to-date specifications of NEC semiconductor products. Not all products
and/or types are available in every country. Please check with an NEC sales representative for
availability and additional information.

- No part of this document may be copied or reproduced in any form or by any means without prior written consent of NEC. NEC assumes no responsibility for any errors that may appear in this document.
- NEC does not assume any liability for infringement of patents, copyrights or other intellectual property rights of third parties by or arising from the use of NEC semiconductor products listed in this document or any other liability arising from the use of such products. No license, express, implied or otherwise, is granted under any patents, copyrights or other intellectual property rights of NEC or others.
- Descriptions of circuits, software and other related information in this document are provided for illustrative
 purposes in semiconductor product operation and application examples. The incorporation of these
 circuits, software and information in the design of customer's equipment shall be done under the full
 responsibility of customer. NEC assumes no responsibility for any losses incurred by customers or third
 parties arising from the use of these circuits, software and information.
- While NEC endeavours to enhance the quality, reliability and safety of NEC semiconductor products, customers
 agree and acknowledge that the possibility of defects thereof cannot be eliminated entirely. To minimize
 risks of damage to property or injury (including death) to persons arising from defects in NEC
 semiconductor products, customers must incorporate sufficient safety measures in their design, such as
 redundancy, fire-containment, and anti-failure features.
- NEC semiconductor products are classified into the following three quality grades:
 "Standard", "Special" and "Specific". The "Specific" quality grade applies only to semiconductor products
 developed based on a customer-designated "quality assurance program" for a specific application. The
 recommended applications of a semiconductor product depend on its quality grade, as indicated below.
 Customers must check the quality grade of each semiconductor product before using it in a particular
 application.
 - "Standard": Computers, office equipment, communications equipment, test and measurement equipment, audio and visual equipment, home electronic appliances, machine tools, personal electronic equipment and industrial robots
 - "Special": Transportation equipment (automobiles, trains, ships, etc.), traffic control systems, anti-disaster systems, anti-crime systems, safety equipment and medical equipment (not specifically designed for life support)
 - "Specific": Aircraft, aerospace equipment, submersible repeaters, nuclear reactor control systems, life support systems and medical equipment for life support, etc.

The quality grade of NEC semiconductor products is "Standard" unless otherwise expressly specified in NEC's data sheets or data books, etc. If customers wish to use NEC semiconductor products in applications not intended by NEC, they must contact an NEC sales representative in advance to determine NEC's willingness to support a given application.

(Note)

(1) "NEC" as used in this statement means NEC Corporation and also includes its majority-owned subsidiaries.
 (2) "NEC semiconductor products" means any semiconductor product developed or manufactured by or for NEC (as defined above).